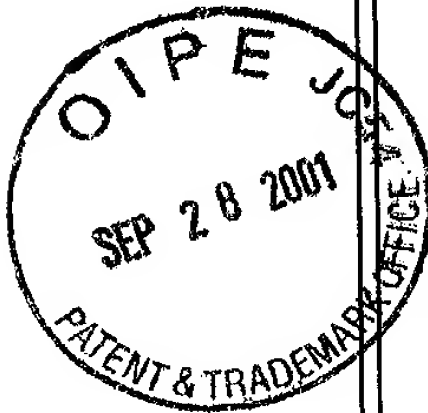


#3 2878  
J. Brunson  
10/11/01



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): Thomas P. Glenn, Steven Webster, Markus K. Liebhard

Assignee: Amkor Technology, Inc.

Title: CHIP SIZE IMAGE SENSOR WIREBOND PACKAGE FABRICATION METHOD

Serial No.: 09/712,314

Filed: November 13, 2000

Examiner: Unknown

Group Art 2878  
Unit:

Docket No.: G0026M

Monterey, CA  
September 25, 2001

ASSISTANT COMMISSIONER FOR PATENTS  
ATTN: Official Draftsperson  
Washington, D.C. 20231

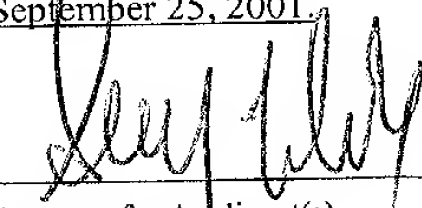
SUBMISSION OF FORMAL DRAWINGS

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Dear Sir:

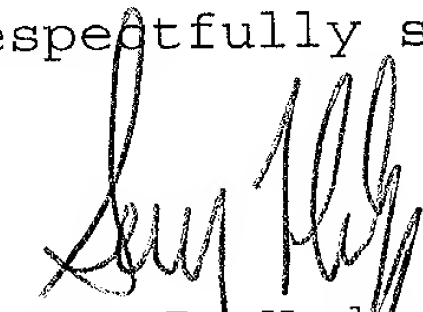
Applicants submit eight (8) sheets of formal drawings consisting of Figures 1, 2, 3, 4, 5, 6, 7A, 7B, 7C, 7D, 7E, 8A, 8B, 9, 10, 11, 12, 13 and 14. If there are any questions concerning the formal drawings, please call the undersigned at the number given.

I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as First Class Mail in an envelope addressed to: Assistant Commissioner for Patents, Washington, D.C. 20231, on September 25, 2001.

  
Attorney for Applicant(s)

September 25, 2001  
Date of Signature

Respectfully submitted,

  
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